



PATENT  
8017-1122

IN THE U.S. PATENT AND TRADEMARK OFFICE

In re application of

Noriaki ODA

Conf. 2345

Application No. 10/761,204

Group 2826

Filed January 22, 2004

Examiner A. Williams

SEMICONDUCTOR DEVICE WITH BONDING PAD SUPPORT STRUCTURE

AMENDMENT

Assistant Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

July 6, 2007

Sir:

In response to the Official Action of May 17, 2007,  
please amend the above-identified application as follows:

**Amendments to the Claims** are reflected in the listing  
of claims which begins on page 2 of this paper.

**Remarks** begin on page 7 of this paper.